

Transaction Information

Tool ID	BSP900
Tool Status	Connected
Location	Dresden, Germany
Wafer Size	300 mm
Fab Section	CMP
Tool Available Date	2024-10-20

General Product Information

Vendor Supplier	LINTECH
Model	RAD-3010F/12
Vintage	2012
Serial No	D13S000801
Asset Description	BSP900-T Remover RAD-3010F/12
Software Version	V1.06
CIM	SECS, GEM
Process	Peeling

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Main System	Mainframe	1	OK
Options System			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status

Missing/Faulty Parts / Accesories List

Description	Quantity
NONE	

Tool Pictures

General	Mainframe
---------	-----------



General

Mainframe



Manufacture Serial

SN-PLate

LINTEC Corporation

MADE IN JAPAN

MODEL : RAD-3010F/12
SERIAL NUMBER : D13S000801

DIAGRAM NUMBER : K12502H
MFG.DATE : OCT-2012

MANUFACTURER : LINTEC Corporation
ADDRESS : 23-23 Honcho, Itabashi-ku, Tokyo 173-0001 Japan

AIR : 0.5~0.8MPa, 150L/min(ANR)
DUCT : 2.7~5.1cbm/min(MAX)
VACCUM : -80kPa or above

VOLTAGE : 200-230V 1PHASE
WIRING CONFIGURATION : 2WIRE+GROUND
FREQUENCY : 50/60Hz
FULL LOAD AMPS : 30A
MACHINE MAIN BREAKER RATING : 40A
AMPERE RATING OF LARGEST LOAD : 25A
INTERRUPT CURRENT : 13000A . I . C .

MASS : 1,100kg